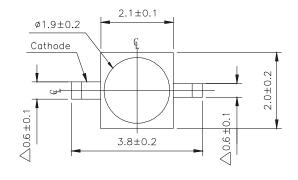
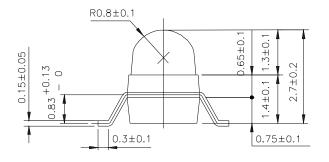
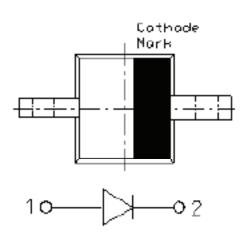


# SPECIFICATION CSM28G2CG-1

### **PACKAGE OUTLINES**







#### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm$  0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CSM28G2CG-1	InGaAIP	Green	Water Clear	20°





## **ABSOLUTE MAXIMUM RATINGS**

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	25	mA	
Reverse Current @ 5V	lR	10	μΑ	
Power Dissipation	Pd	60	mW	
Operating Temperature Range	Тор	-40~+85	°C	
Storage Temperature Range	Тѕтс	-40~+100	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lFP	60	mA	
Soldering Temperature	TsoL	Max 260°C for	5 sec Max	

# **OPTICAL-ELECTRICAL CHARACTERISTICS**

(TA=25°C)

Darameter	Symbol	Toot Condition	Value			Linit
Parameter		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	200	600	-	mcd
Forward Voltage	VF	IF = 20mA	1	2.0	2.4	V
Reverse Leakage Current	lR	VR = 5V	-	-	10	μΑ
Viewing Angle at 50% Iv	201/2	IF = 10mA	ı	25	-	Deg
Peak Wavelength	λР	IF = 20mA	-	575	-	nm
Dominant Wavelength	λD	IF = 20mA	565	570	575	nm

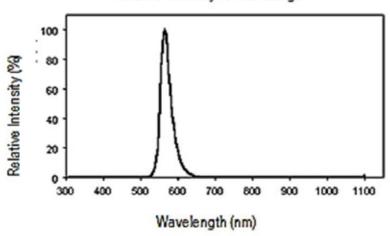
<sup>\*</sup>Tolerance of viewing angle: -10 / +5 deg.



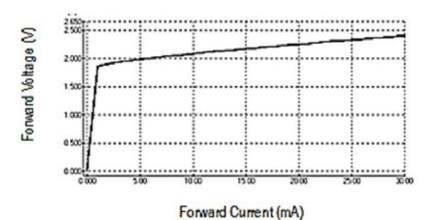


# **OPTICAL CHARACTERISTIC CURVES**

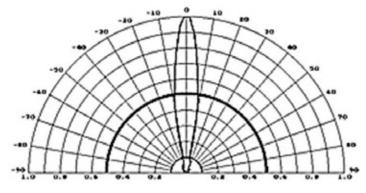
### Relative Intensity vs. Wavelength



#### Forward Current vs. Forward Voltage



# Directive Characteristics

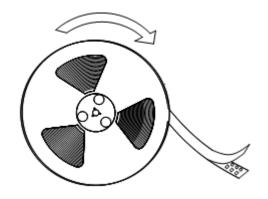




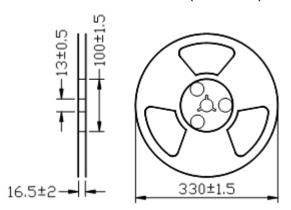


## **PACKAGING SPECIFICATION**

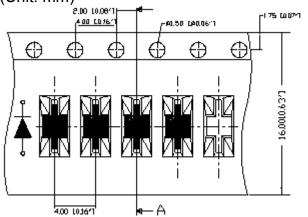
#### **Feeding Direction**

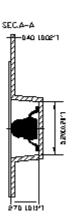


### Dimensions of Reel (Unit: mm)

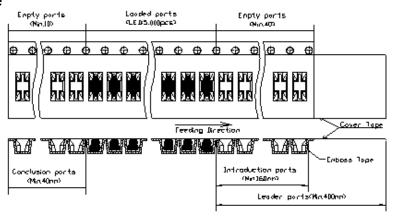


### Dimensions of Tape (Unit: mm)





#### Arrangement of Tape



#### Notes:

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamp is two;
- 3. The cathode is oriented towards the tape sprocket hole;
- 4. 1,000 pcs/Reel

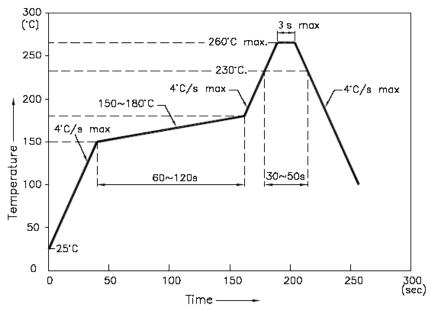




## **SOLDERING CONDITIONS**

#### **REFLOW PROFILE**

#### Reflow Temp/Time



#### Notes:

- 1. We recommend the reflow temperature 245°C ( $\pm 5$ °C). The maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process should be 2 times or less.

#### Soldering Iron

Basic spec is  $\leq$  5 sec when 260°C. If temperature is higher, time should be shorter ( $\pm 10^{\circ}\text{C} \rightarrow -1\text{sec}$ ). Power dissipation of iron should be smaller than 20W and temperature should be controllable. Surface temperature of the device should be under 230°C.